PCN Number:		20231005001.2							PCN Date:		October 06, 2023	
Title:		Adding TI CD-PR as additional wafer probe (EWS) site										
Customer Contact:		Change Management team Dep					t: Quality Services					
Proposed 1 st Ship Da		te: Apr 00		06, 2024					Samp	oles not orted		
Cha	ange Type:					•	_					
	Assembly Site				Design				Wafer Bump Material			
	Assembly Proc	ess			Data Sheet				Wafer Bump Process			
	Assembly Mate				Part number change		ge		Wafe	Wafer Fab Site		
	Mechanical Specification			\boxtimes	Test Site				Wafer Fab Material			
	Packing/Shipp	ng/Labeling			Test Process				Wafer Fab Process			
PCN Details												
Description of Change:												
Texas Instruments Incorporated has qualified TI CD-PR as additional probe (EWS) site for the devices listed below to support high volume ramps.												
			C	ırrant				N	OW:			
Probe Site (EWS) MAINEFAB TI CHENGDU (CD-PR) Test coverage, insertions, conditions will remain consistent with current testing.												
Tes	,	,	MAINEF			nt witl	I	IEN			<u>R)</u>	
	,	,	MAINEF	AB		nt witl	I	IEN	GDU (R)	
Rea	st coverage, inserti	ons, cond	MAINEF ditions w	AB vill rei	main consister		h curre	IEN	GDU (R)	
Rea	st coverage, insertion	ons, cond	MAINEF ditions w y to sup	vill rei	main consister high volume r	amps.	h curre	ent t	GDU ((
Rea	ason for Change: able additional probe	ons, cond	MAINEF ditions w y to sup	vill rei	main consister high volume r	amps.	h curre	ent t	GDU ((
Rea Ena Ant	ason for Change: able additional probe	capacit	MAINEF ditions w y to sup	vill repopert	main consister high volume r	amps.	h curre	ent t	GDU ((
Rea Ena Ant	ason for Change: able additional probe ticipated impact one. anges to product in	capacit	MAINEF ditions w y to sup	vill repopert	main consister high volume r	amps.	h curre	ent t	GDU ((
Rea Ena And Nor Cha	ason for Change: able additional probe ticipated impact one. anges to product in	capacit	MAINEF ditions w y to sup	vill repopert	main consister high volume r	amps.	h curre	ent t	GDU ((

ZVEI ID reference: SEM-TF-01

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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